IPC ASSOCIATION ELECTRONIE	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights rinternational and Pan-American copyright conventions.			nder both	This document is a declaration of the substate level parts, the declaration encompasses all level parts.				within the materi	anufacture als for whi	r listed ite ich the ma	m. Note: if nufacturer	f the item is an as has engineering	sembly with low responsibility.
752-21.1					Form Type * Distribute	:	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information			
Supplie	r Information														
Company name*				Company unique ID			Unique ID Authority					Response Date*			
onsemi												2024-04-19			
Contact N	Name	Title - Contact			P	Phone - Contact*					Email - Contact*				
Product-	Env-Stewards		Product Enviro Compliance			1	NA					Product-Env-Stewards@onsemi.com			
uthorize	ed Representative*	Title - Representative			P	Phone - Representative*				Email - Representative*					
Product-	Env-Stewards	Product Enviro Compliance			1	NA					Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr		tem Number Mfr Item Name				Effective Date	Versio	Version Manufacturing Site		g Site	W	eight*	UOM	Unit Type
		NCP1117DT18T5G ANA LO E		ANA LO DIF 8001	IF 800MA POS REG		2024-04-19 MY		MY1		35	0.99	mg	Each	
Ianufa	acturing Process Inform											1		,	
			The state of the s		-STD-020 MSL	Rating	Peak Process Body Temperati					т.		er of Reflow Cyc	eles
	Matte Tin (Sn) - annealed		CU Alloy	1			260		C	30		second	3		
omments	•														
	naximum time at peak tempera														
r more	information regarding materia	al composition	please refer to	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
irective 2015/863/EU amending RoHS irective 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale app											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.2	mg	Supplier	Silicon (Si)	7440-21-3		0.2	mg
Die Attach	1.4	mg	A	Lead (Pb)	7439-92-1	7a	1.33	mg
			Supplier	Tin (Sn)	7440-31-5		0.07	mg
Lead Frame	214.64	mg	В	Nickel (Ni)	7440-02-0		0.4293	mg
			Supplier	Copper (Cu)	7440-50-8		214.2107	mg
Mold Compound-Black	129.65			Epoxy resin	proprietary data		9.0755	mg
			Supplier	Phenolic Resin	Proprietary Data		9.0755	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		19.4475	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6482	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		91.4032	mg
Plating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg
Wire Bond - Cu	1.37	mg	Supplier	Copper (Cu)	7440-50-8		1.37	mg